

# Delta Liquid Cooling Solution

tMPBU | FMBG  
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【お問い合わせ先】

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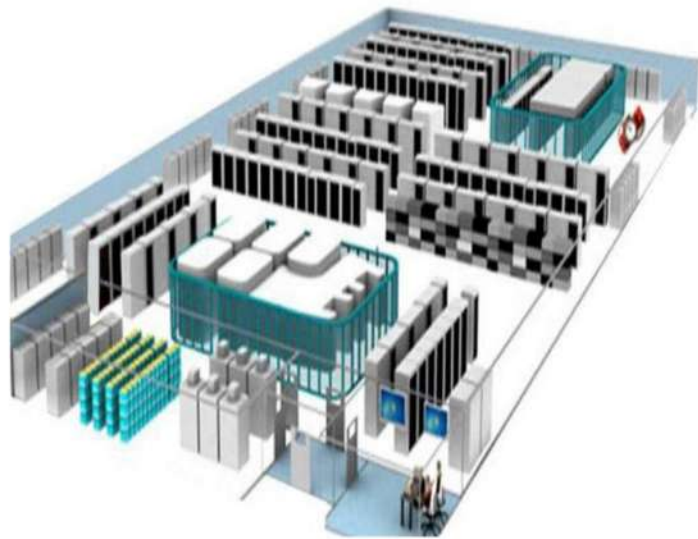
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# Delta Liquid Cooling Solution Portfolio

Big Data

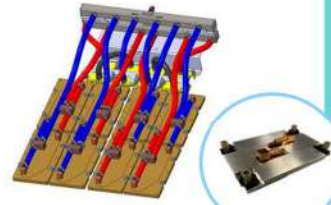
High Performance Computing

AI



Data Center Construction

## Server Level



Closed loop (assisted air)  
Open loop (assisted air/ facility water)

## Rack Level



Liquid to Air CDU  
Liquid to Liquid CDU

## System level



Manifold  
In-row CDU  
Immersion Cooling

## Feature

- Various high performance standard cold plate for data center liquid cooling
- Optimization for cold plate and loop design
- Integrating Delta DC fan and DC pump



Cold plate

Cold plate loop solution

## Feature

- Low power consumption
- Integrating Delta fan and pump
- Redundant pump design



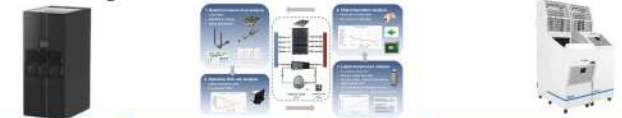
L-A CDU

RPU

L-L CDU

## Feature

- High cooling capacity in row CDU
- Standardized, modularized design for immersion cooling solution



In-row CDU

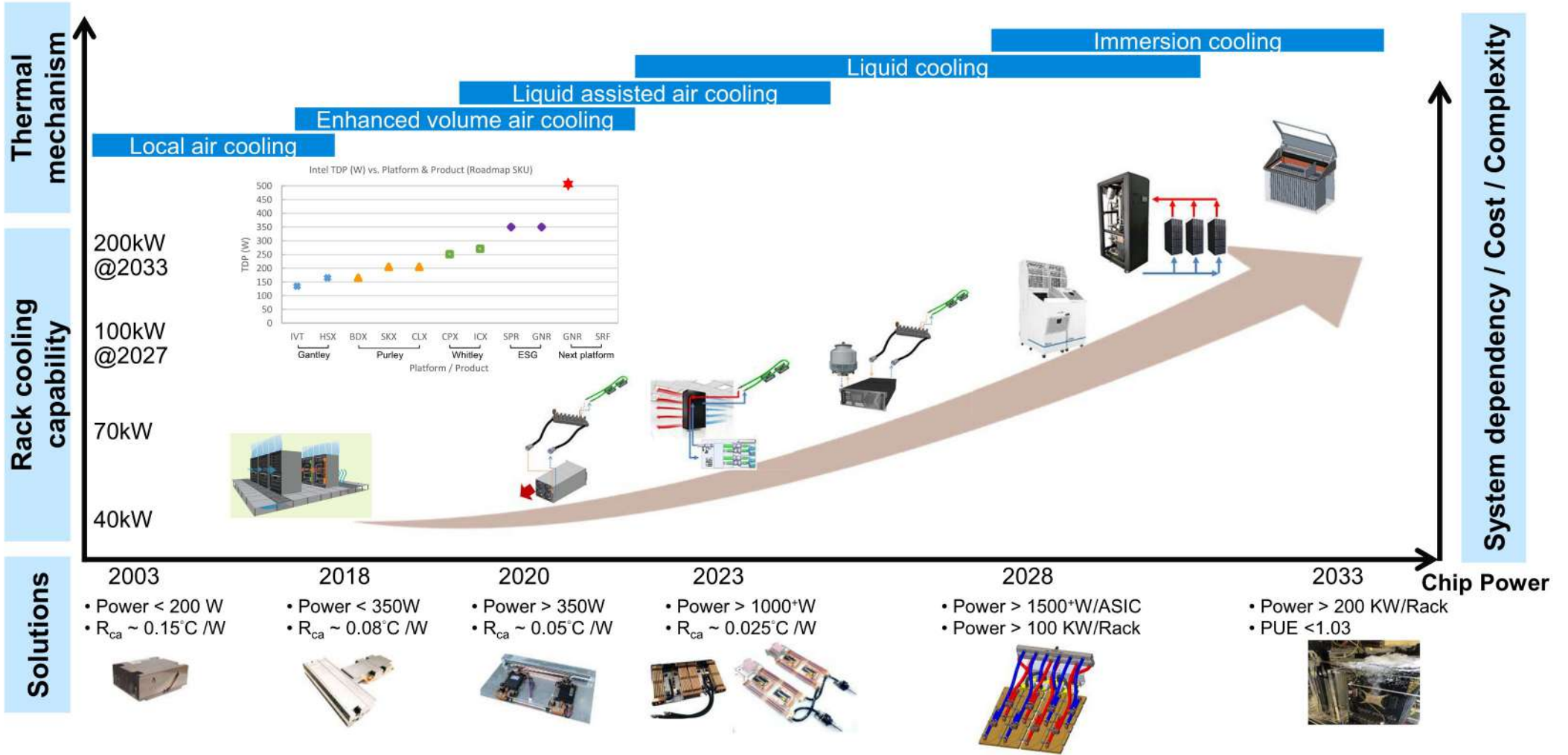
Optimization LCS process

Immersion cooling

RPU: Reservoir pumping unit

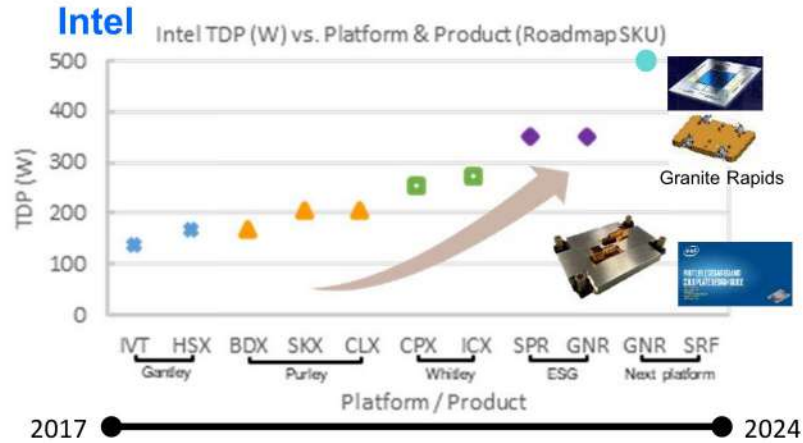


# Data Center Thermal Solution Resolution

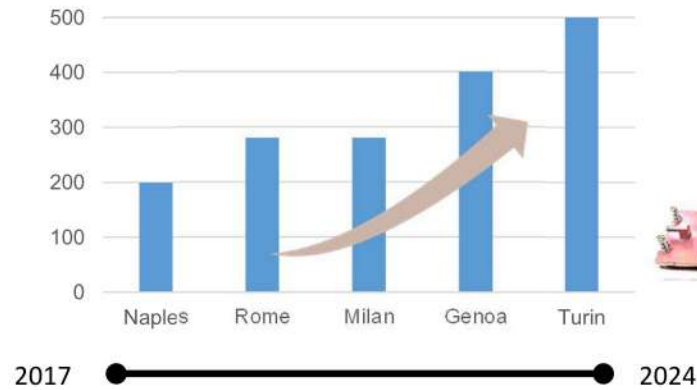


# Commodity CPU/GPU vs Delta Cold Plate Solution

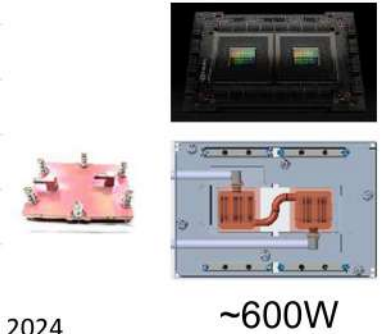
CPU



AMD



nVIDIA – C2



GPU

GPU Model	Approximate TDP (W)
AMD- MI200	~560W
AMD- MI300C	~550W
nVIDIA – SXM4	~500W
nVIDIA – SXM5	~700W
nVIDIA – GH200	~1000W



# Commodity CPU Cold Plate Performance

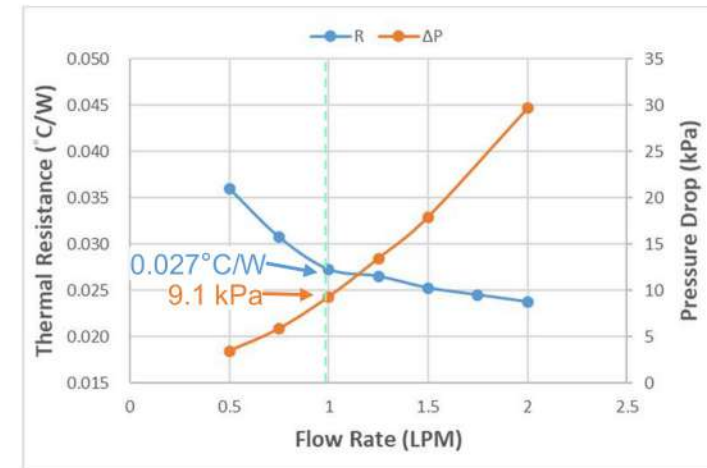
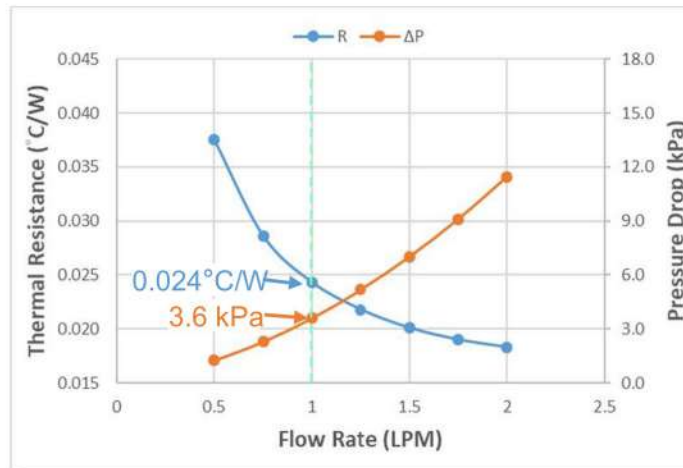
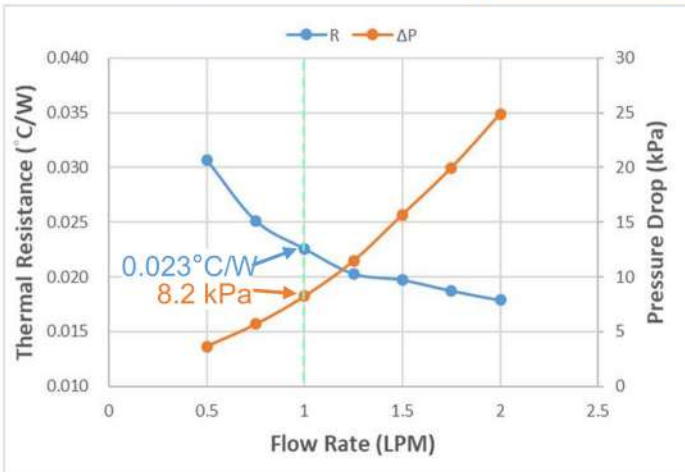
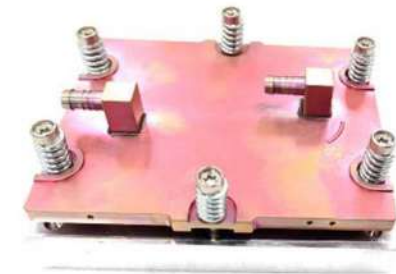
- Model: Intel Sapphire Rapids
- TDP: 350 W
- Stage: MP



- Model: Intel Granite Rapids
- TDP: 500 W
- Stage: 2023/Sep MP



- Model: AMD Genoa
- TDP: 400 W
- Stage: MP



Intel doc#: 602060  
 Approved by Intel as LCS ecosystem solution listed in design guideline

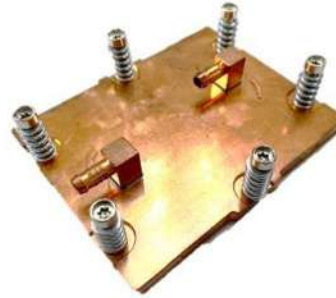


# Commodity GPU Cold Plate Performance

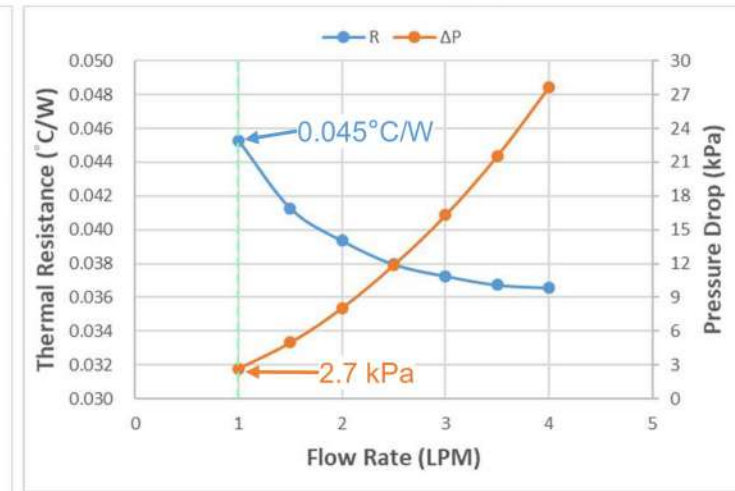
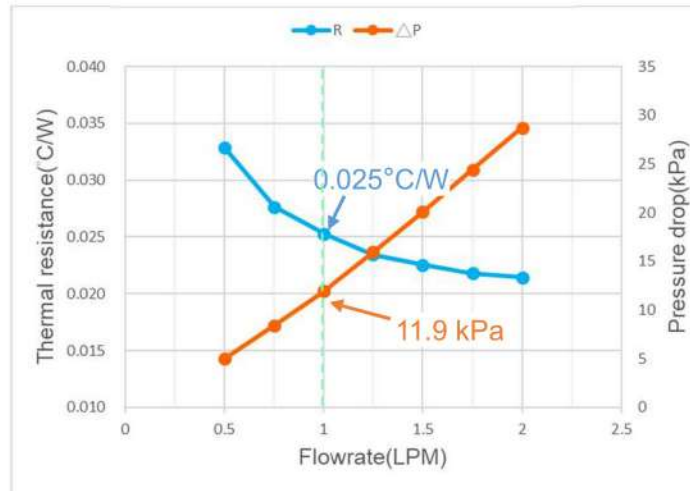
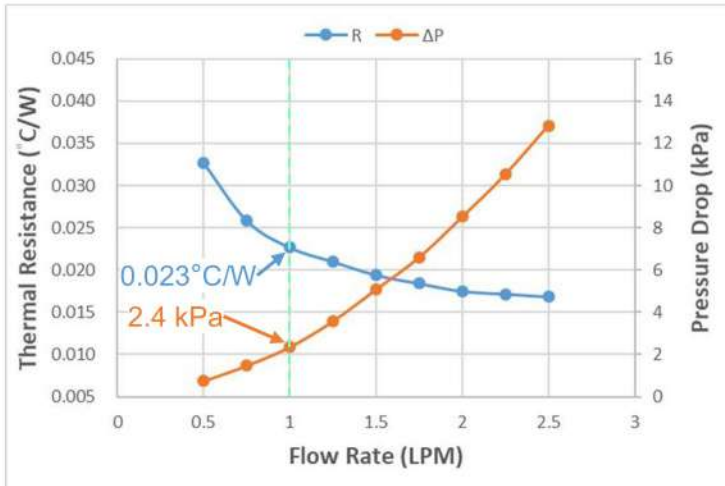
- Model: AMD MI200
- TDP: 560 W
- Stage: MP



- Model: AMD MI300 C
- TDP: 550 W
- Stage: MP

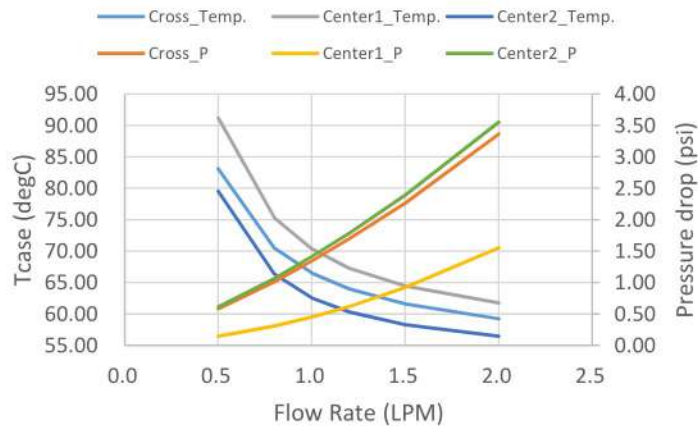
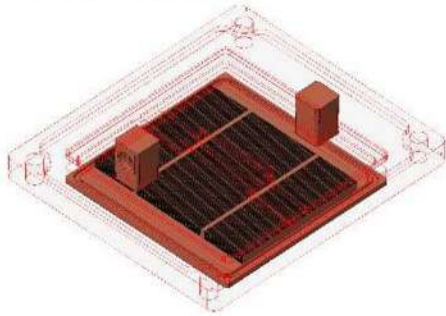


- Model: nVIDIA H100
- TDP: 700 W
- Stage: MP



# High TDP Liquid Cooling Technology - 1.5KW ASIC

- Heat source : 70x70 mm
- Power: 1500W
- Coolant : PG25

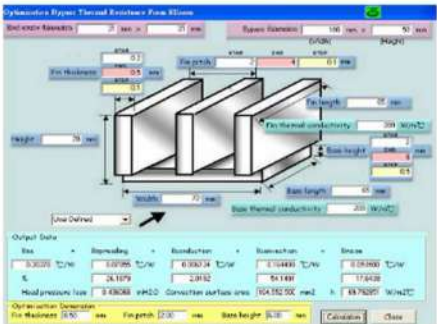


	Version A	Version B	Version C
Flow schematic	Cross flow	Low flow impedance design	Low thermal resistance design
Fin Density (FPI)	84.6	84.6	84.6
Fin Width (mm)	70.0	70.0	70.0
Fin thickness (mm)	0.15	0.15	0.15
Flow rate (LPM)	1.0	1.0	1.0
Thermal Resistance (°C/W)	0.0190	0.0216	<b>0.0164</b>
T <sub>inlet</sub> (°C)	38.0	38.0	38.0
T <sub>case</sub> (°C) , center of lid	66.5	70.4	62.6
Pressure drop (psi)	1.34	<b>0.45</b>	1.41
Temperature distribution			

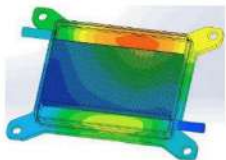
Ready technology for high thermal design power ASIC

# Cold Plate Technology

## ■ Analysis Tool – Self-developed Program/ Simulation Software



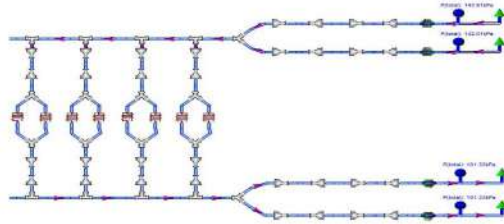
Self-developed program



**ANSYS** icepak



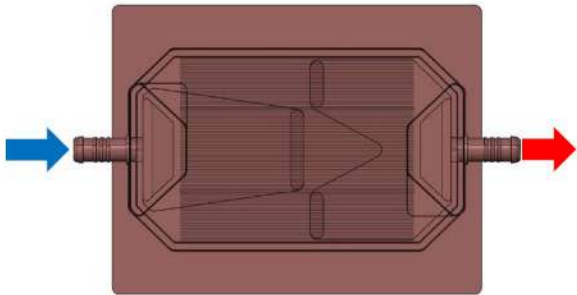
**FloTHERM**<sup>®</sup>



## ■ Cold Plate Design Technology



Impingement flow design  
 Pressure Impedance 15% ↓

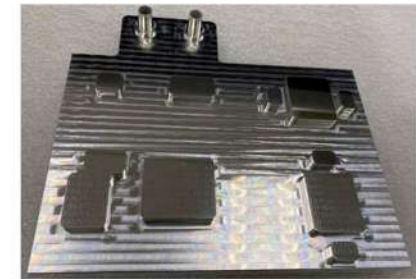
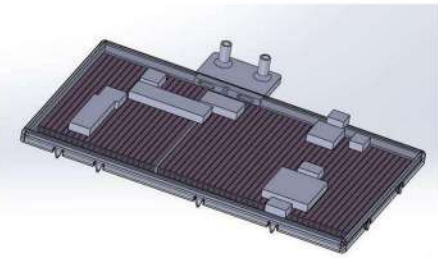


Impingement flow & reflow design  
 Performance 10% ↑ with Same Pressure Impedance

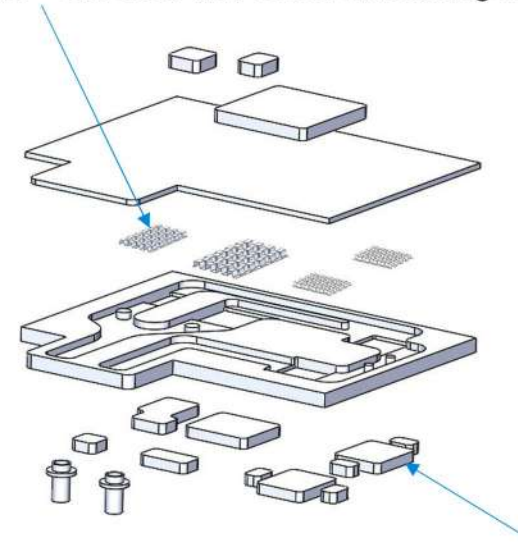
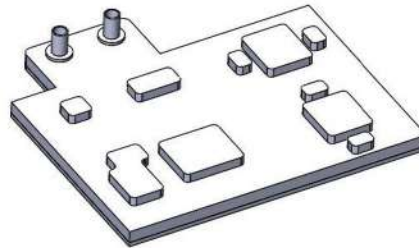
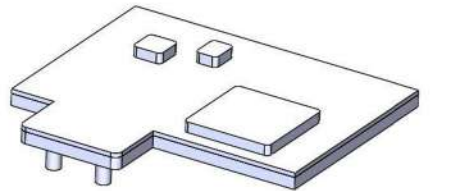


# AL Brazing Cold Plate

- Inner structure – Stacked fin/Folded fin/Skiving fin can be selected



Brazing coldplate



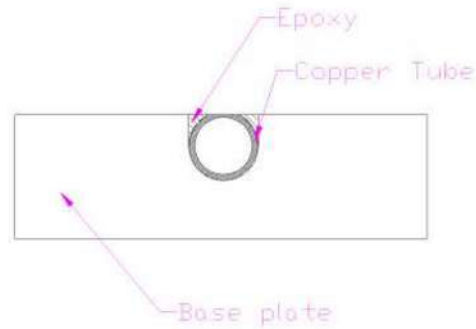
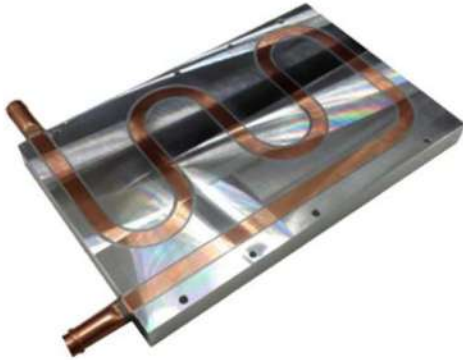
- Multiple heat sources contact



## Capacity

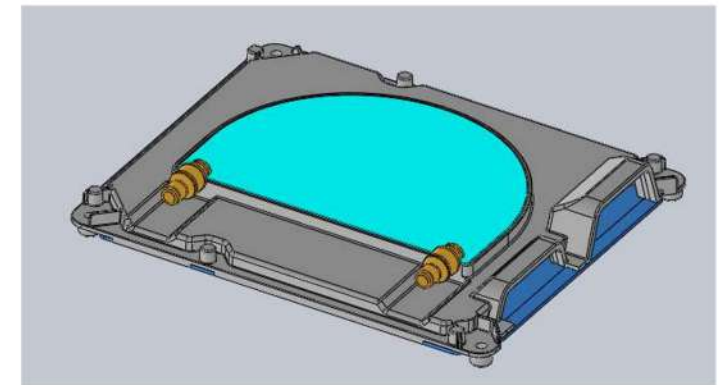
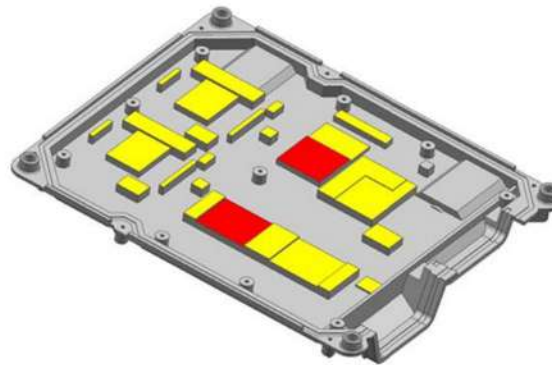
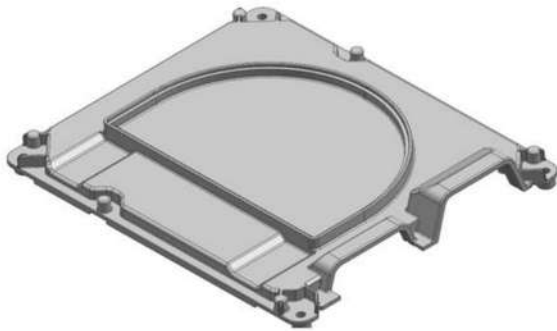
- Composite material
- Brazing material
- Various fin structure:
  - extrusion/stacked fin/skive fin/Folded fin
- Stacked fin:
  - fin thickness: 0.3mm; fin gap: 0.5mm

## Tube Embedded Cold Plate



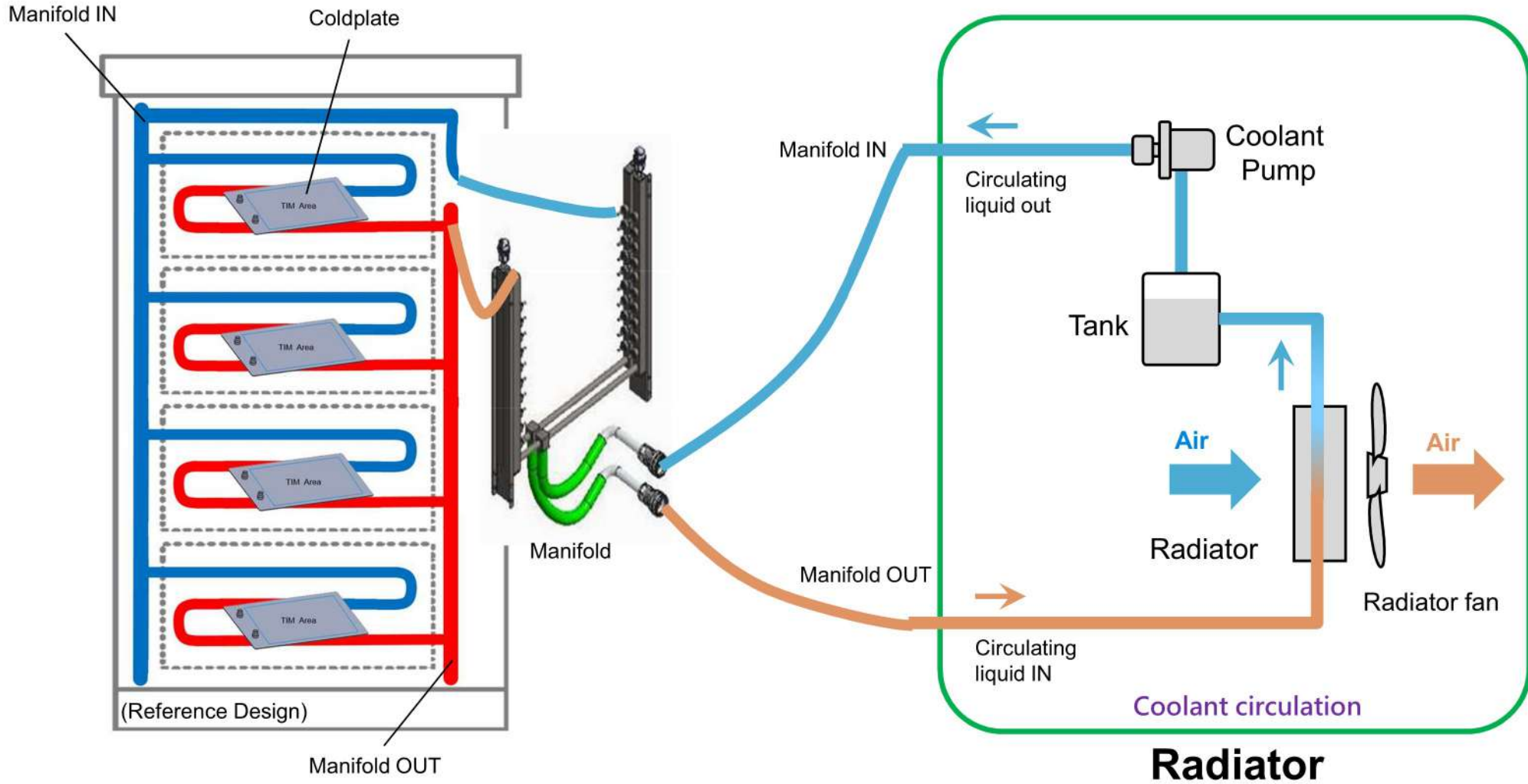
### Capacity

- Al/Cu base
- C12200 tube material
- High thermal conductivity epoxy
- Tube exposed



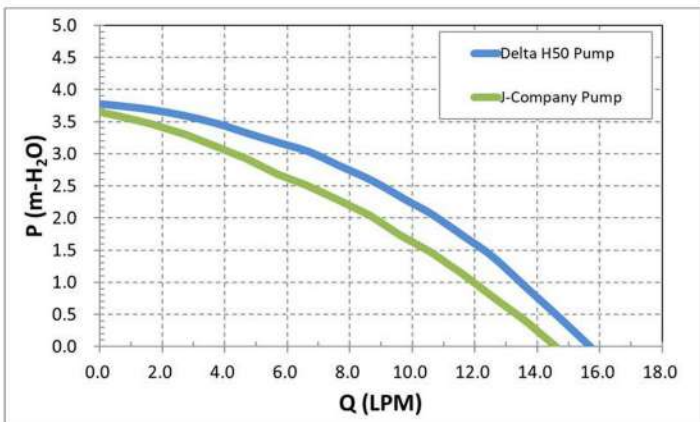
- By using copper tube embedded in **die casting** to handle the heat for control unit

# Radiator option proposal



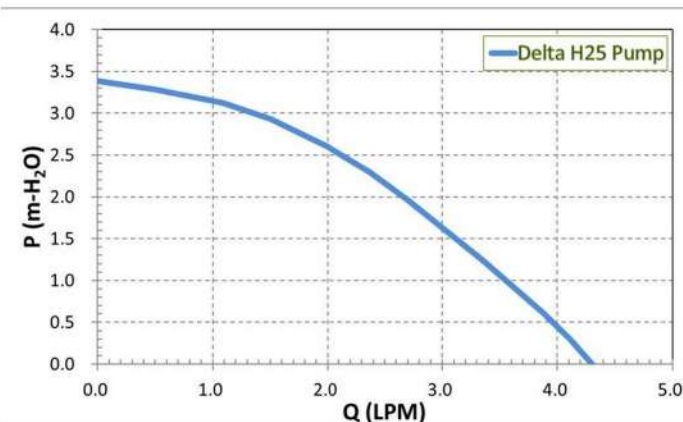
# Delta Pump Performance

## 2U Application (H50mm)



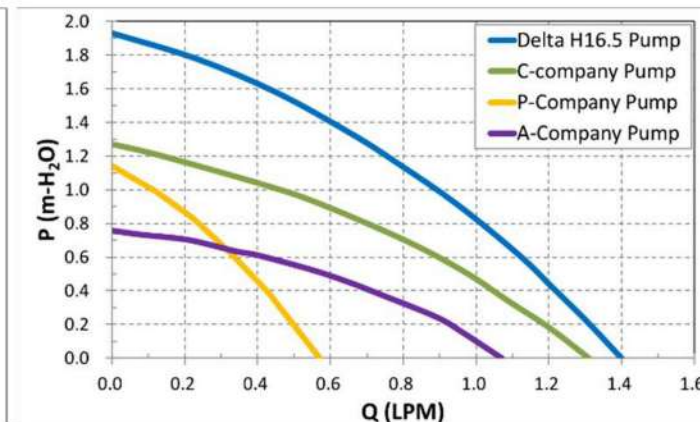
Verified MTTF 50 °C (hrs)	2,077,723
Verified L <sub>10</sub> 50 °C (hrs)	296,818

## 1.5U Application (H25mm)



Verified MTTF 50 °C (hrs)	532,407 (Processing)
Verified L <sub>10</sub> 50 °C (hrs)	76,058 (Processing)

## 1U Application (H16.5mm)



Verified MTTF 50 °C (hrs)	775,632
Verified L <sub>10</sub> 50 °C (hrs)	110,805

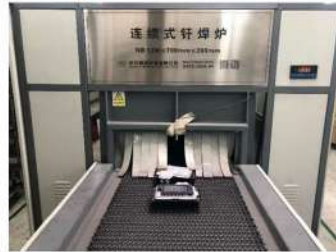
With self-developed technology  
Delta pump features both high PQ performance with long life expectancy

# Liquid Cooling Solution Manufacturing Capability

■ Brazing oven - Copper



■ Brazing oven - Aluminum



■ Brazing material dispenser



■ Welding



■ Flow & Thermal Testing



■ Cleaning



■ Drying



■ Vacuum Oven



■ Helium Testing



■ Run In & Burn In Chamber



■ Pressure Holding Test



■ Pressure Pulse / Decay Test



■ Reliability : Burst Test



In-line process/testing and inspection for quality control

# Coolant Distribution Unit

## Liquid to Liquid CDU

Model:DHS-X430175-01



- 4U height
- 450 (W) x 900 (D) x 175 (H) mm
- Cooling capacity: 100 kW @ $T_{\text{approach}}=18^{\circ}\text{C}$
- Full load power consumption: 580 W
- Modbus / Redfish / Webserver
- Smart self-protection & High performance pump
- Facility chiller
- Comply UL 62368



Intel doc#: 636703  
 Approved by Intel as LCS ecosystem solution  
 listed in design guideline

## Liquid to Air CDU

Model:FHS-X440350-01



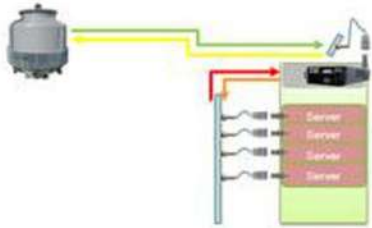
- 8U height
- 450 (W) x 900 (D) x 350 (H) mm
- Cooling capacity: 14 kW @ $T_{\text{approach}}=25^{\circ}\text{C}$
- Full load power consumption: 2,200 W
- Modbus / Redfish / Webserver
- Smart self-protection &
- High performance pump & fan
- CDU cooling fan
- Comply UL60335



Approved by Intel as liquid cooling solution ecosystem listed in design guideline

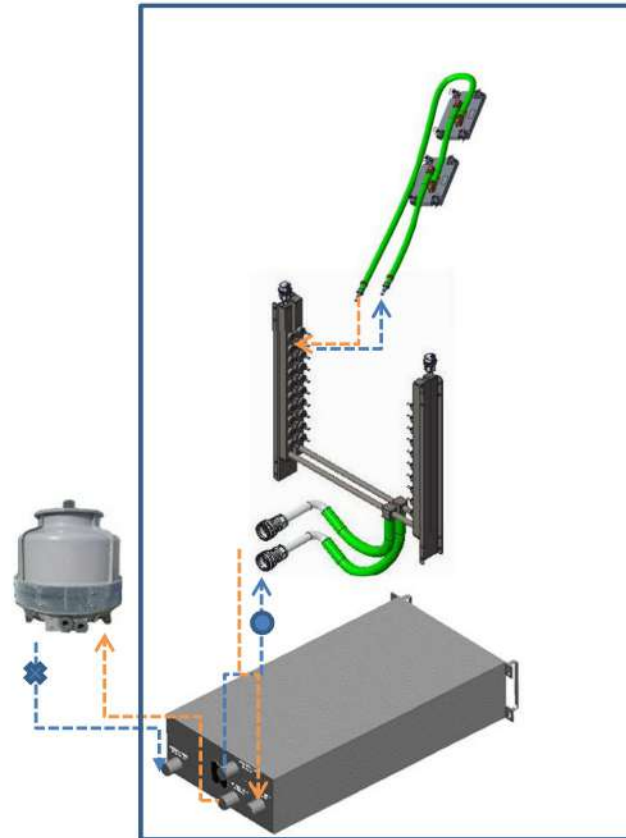
# Coolant Distribution Unit – Liquid to Liquid

## Liquid to Liquid CDU



Liquid to liquid CDU (4U height)

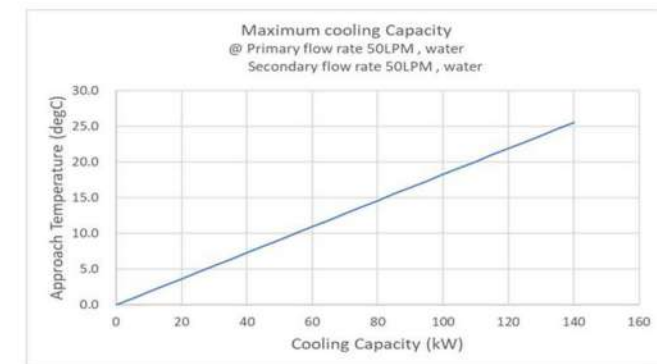
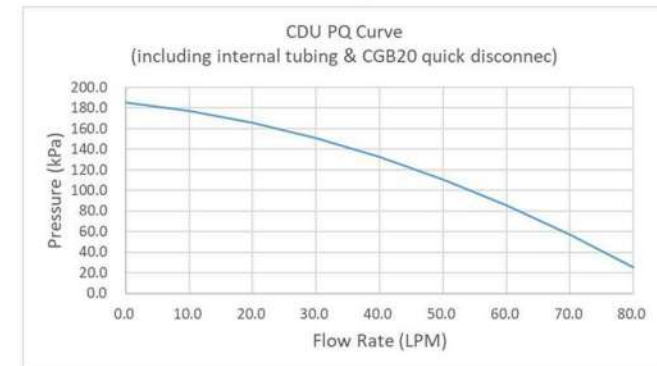
- **Need facility chiller**
- 450 (W) x 900 (D) x 175 (H) mm
- Cooling capacity is 100 kW @ approach temperature = 18°C
- Pressure control/  
Dew point temperature control/  
Liquid flow control/
- Redundant pump design
- Leakage and condensation alarm
- Power consumption: 580 W
- Low power consumption



T app (Approach temperature)  
= Secondary supply (●) – Primary supply (✳)

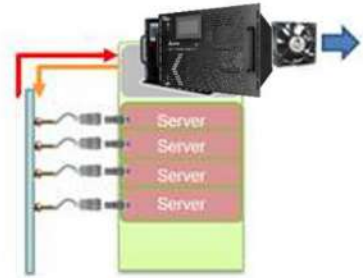


PQ Curve of CDU



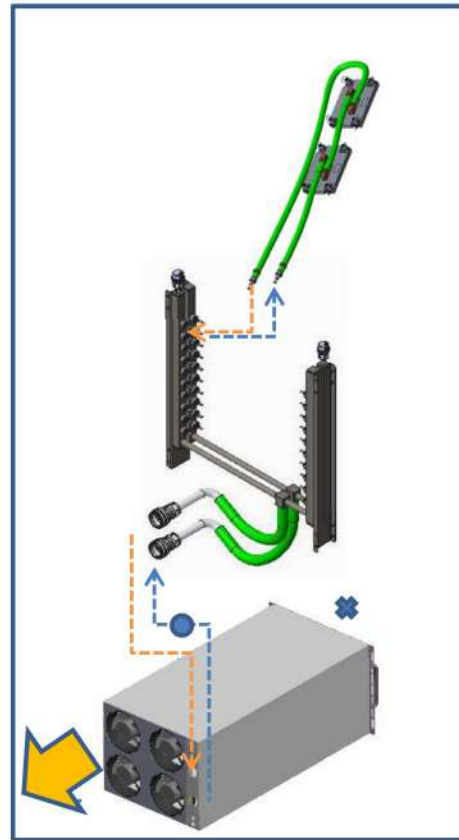
# Coolant Distribution Unit – Liquid to Air

## Liquid to Air CDU

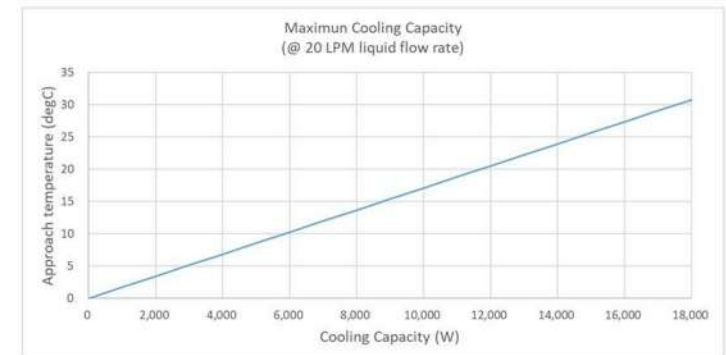
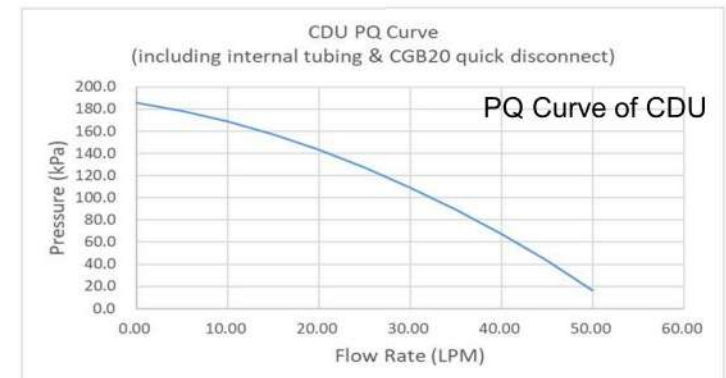


Liquid to Air CDU (8U height)

- **No need facility chiller, easy to build up liquid cooling solution**
- 450 (W) x 900 (D) x 350 (H) mm
- Cooling capacity is 14 kW @ approach temperature = 25°C
- Pressure control/  
Liquid flow control/  
liquid-air heat exchange
- Redundant pump design
- Leakage alarm
- Power consumption: 2,000 W



$T_{app}$  (Approach temperature)  
= Secondary supply (●) – Primary supply (✳)



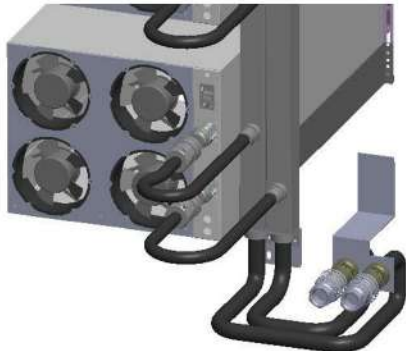
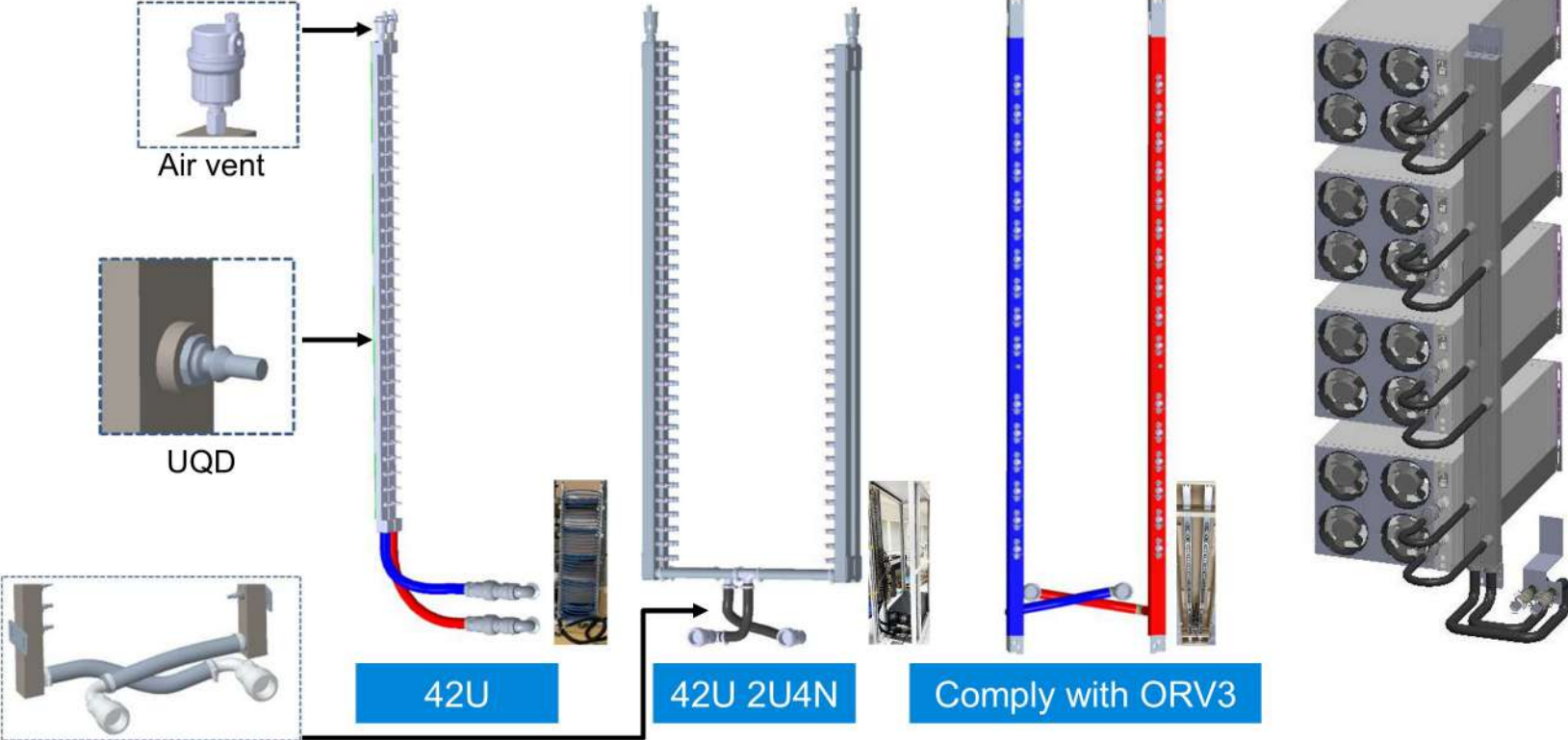


# Manifold Design Capability

■ **Manifold design**

- Customized per demand
- QD selection
- Highly reliable
- Easy to use
- Materials compatibility

- Hose consideration
- Fluid compatibility
- Wetted material consideration

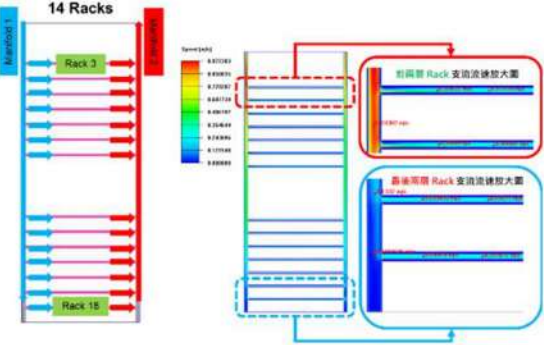
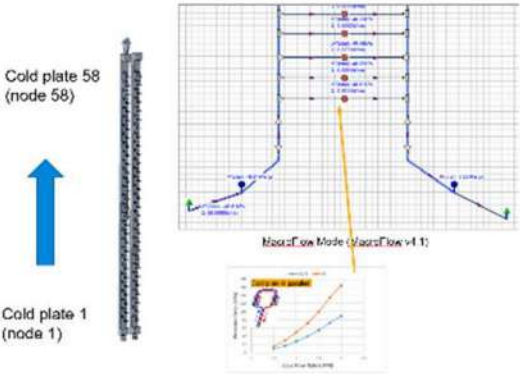


# Manifold Design Capability

## Even Distribution

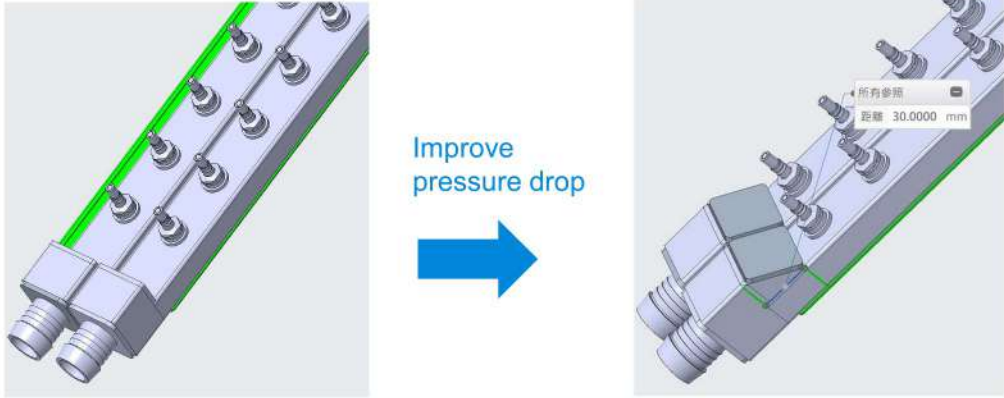
### Manifold Distribution Analysis

Manifold  
• Total 58 nodes (58 cold plate loops)

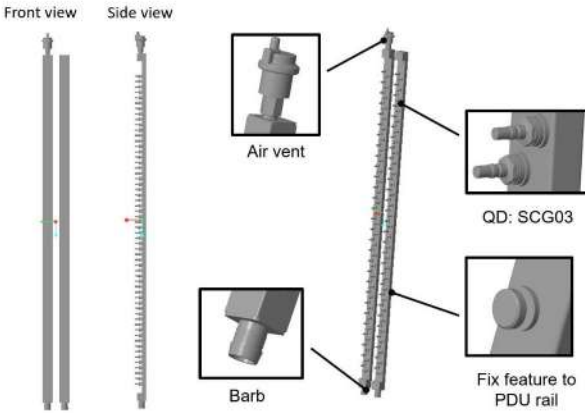


Rack 1 (LPM)	Empty
Rack 2 (LPM)	Empty
Rack 3 (LPM)	1.630
Rack 4 (LPM)	1.626
Rack 5 (LPM)	1.618
Rack 6 (LPM)	1.611
Rack 7 (LPM)	1.605
Rack 8 (LPM)	1.600
Rack 9 (LPM)	1.596
Rack 10 (LPM)	Empty
Rack 11 (LPM)	Empty
Rack 12 (LPM)	1.586
Rack 13 (LPM)	1.584
Rack 14 (LPM)	1.582
Rack 15 (LPM)	1.580
Rack 16 (LPM)	1.579
Rack 17 (LPM)	1.579
Rack 18 (LPM)	1.579
Average $\bar{x}$ (LPM)	1.597
standard deviation $\sigma$ (LPM)	0.018
$\Delta P_{total}$ (Pa)	12832.5
Total Flow Rate (LPM)	22.4
Flow Uniformity ( $\sigma/\bar{x} \times 100\%$ )	1.109 %

## Low Pressure Drop



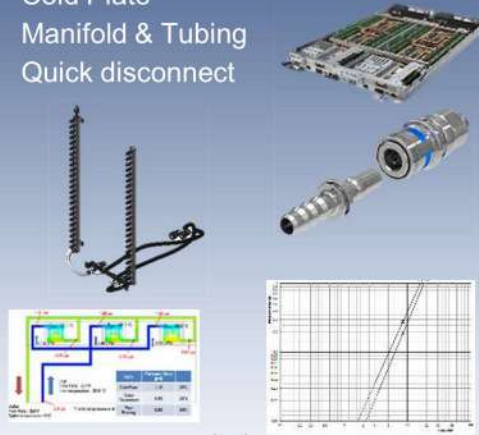
## Customized per Demand



# Integration Capability for Total Liquid Cooling Solution

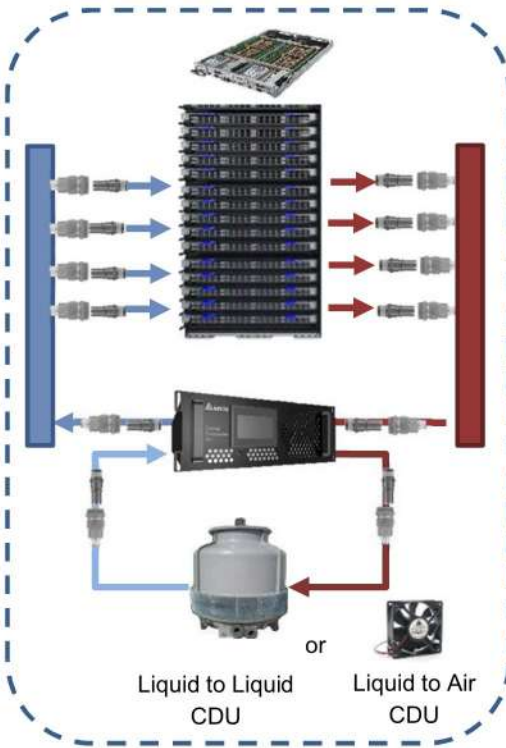
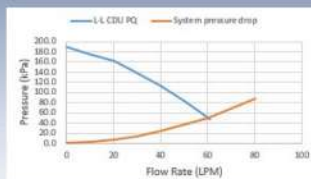
## 1. System pressure drop analysis

- Cold Plate
- Manifold & Tubing
- Quick disconnect



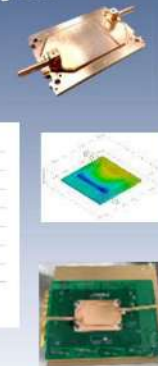
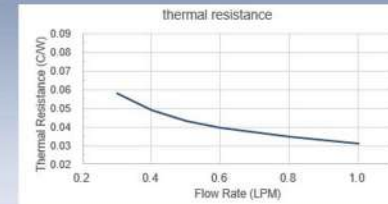
## 2. Operation flow rate analysis

- System pressure drop
- PQ curve of CDU



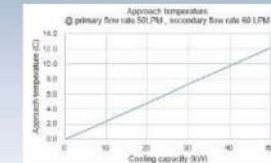
## 4. Chip temperature analysis

- Flow rate of cold plate
- RQ curve of cold plate



## 3. Liquid temperature analysis

- Secondary flow rate
- Primary water flow rate
- Primary water supply temperature
- Heat load of rack
- CDU thermal performance curve (Cooling capacity vs. app. temperature)



Facility water assumption: (Primary side)	
Primary flow rate (LPM)	50.0
Primary supply temperature (°C)	32.0
Secondary side output :	
Total Heat load (kW)	30.0
Secondary flow rate (LPM)	59.9
Secondary supply temperature (°C)	28.3
Secondary return temperature (°C)	28.9



# CDU Manufacturing Capability

## ■ CDU Production Line



## ■ Intelligent Visual Image Detection



## ■ Smart screwdriving system



## ■ Function Test

Equipment Coolant: Dow PG25%  
 Equipment Filter mesh:25um  
 Equipment PH Monitor: 8.0~10.5

报警: OK  
 故障: OK

## ■ Burn-in Test

Equipment Coolant: Dow PG25%  
 Equipment Filter mesh:25um  
 Equipment PH Monitor:8.0~10.5

报警: OK  
 故障: OK

## ■ Drying & Filling

Filling with Nitrogen